

主要材料/BOM 清单信息(Information of Material/BOM list):

样品验证，禁止量产！

材料			描述	供应商
1	基板	S23023JL1E	93. 81X93. 81X0. 21	客供
2	晶圆	WUM230SD1M	A芯 837. 8*966. 5 (μ m ²) *200um (不包含bump高度)	客供
3	助焊剂	TACFLUX 026S	/	钢泰

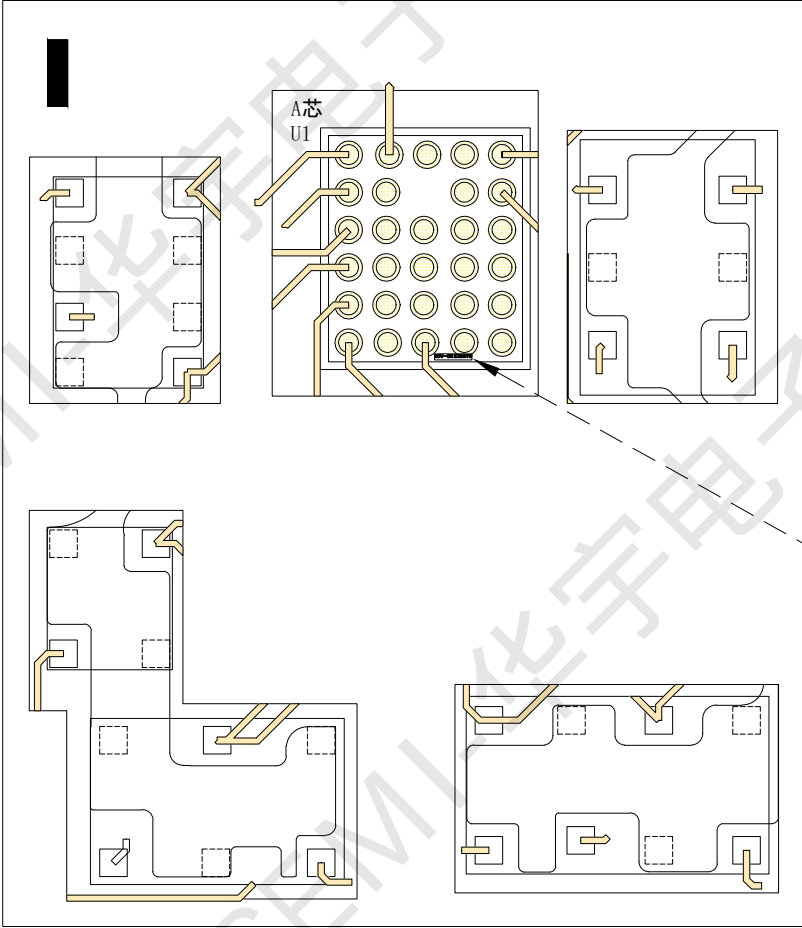
基板切割道宽度	0.09mm
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拟制 Prepared by		制图日期 Create Date	2026/1/7	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

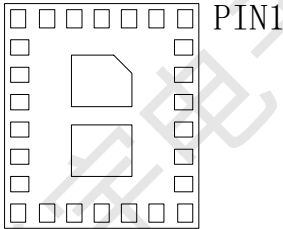
*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
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 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.	1200	线图号 Drawing No.	HY-PX-1200-085 A		页码 Page 2/ 4
	产品名称 Product Type	STR21230-23 E2.0		封装外型 PKG Type	FCLGA28L(3.2X3.7X0.65-P0.45)	
助焊剂 Flux	/	/	/	/	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
TACFlux026S	/	/	/	/	首选(Preferred): / 备选(Optional):	S23023JL1E
客户图号 Customer drawing NO.						
站别	FC	样品验证，禁止量产！				

PIN1

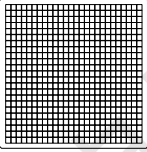


STR21230-V01



底部示意图

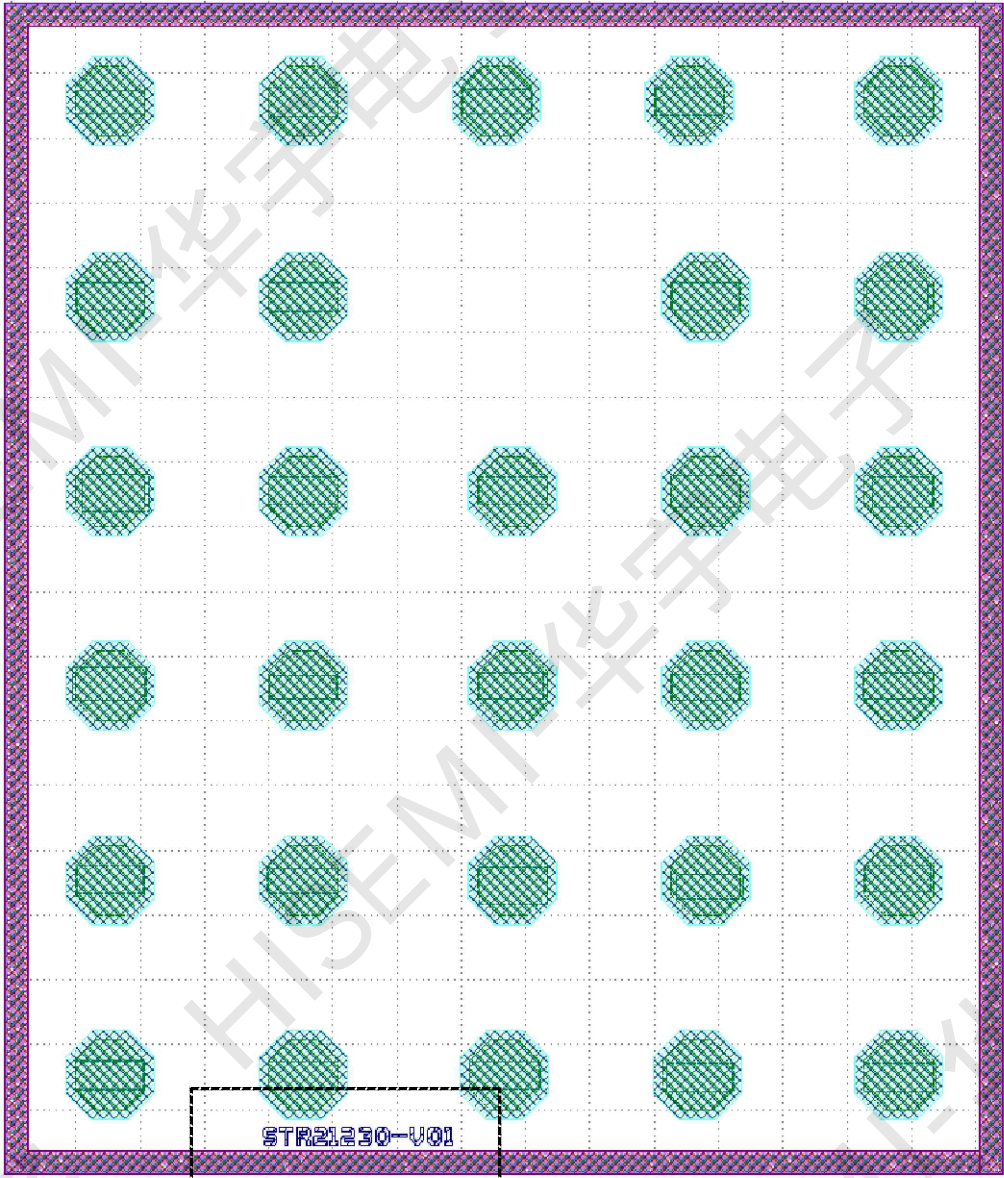
注意：
1.此图纸只做FC倒装贴U1这颗die,U1按照MAP取die;

框架传送方向（装片）： L/F Direction (D/A)：				实物图： Chip photo：				特殊说明 Special Instructions：						
 按单颗显示方向进料														
序号	芯片名称	Die ID	芯片尺寸 (with scribe line)	晶圆尺寸 (Wafer size)	划片道宽度	圆片工艺	芯片厚度 UM	来料方式	Wafer material*	Bump type*	Bump composition*	Min bump pitch (space + bump size)* UM	Min bump height* UM	Min bump diameter* UM
A芯 U1	WUM230SD1M	STR21230-V01	837.8*966.5(μm²) 32.98*38.05(mil²)	8寸	62um	NA	200um (不包含bump高度)	晶圆wafer	SOI	Copper Pillar Bump	35cu+3NI+30Sn	150	68	80
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	产品名称 Product Type	STR21230-23 E2.0		封装外型 PKG Type	FCLGA28L(3.2X3.7X0.65-P0.45)	

U1 ball map图 (TOP view)

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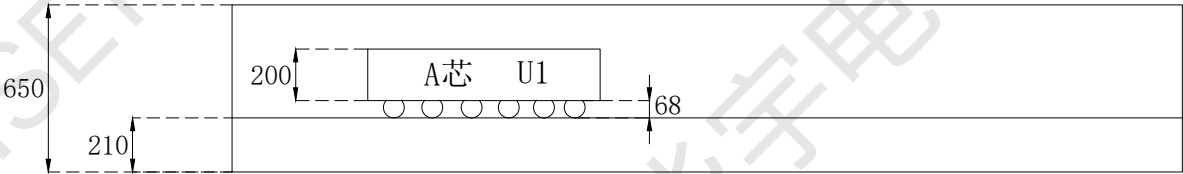
按目标区域取DIE:
ID: STR21230-V01

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